

ABSTRACT

WAFER PRODUCING METHOD AND PROCESSING FEED DIRECTION

DETECTING METHOD

A wafer producing method of producing a wafer from an ingot includes a processing feed direction detecting step of confirming whether or not a direction in which a c-axis of the ingot is inclined and a second orientation flat of the ingot are perpendicular to each other, and detecting a processing feed direction perpendicular to the direction in which the c-axis is inclined. The processing feed direction detecting step includes: a sampling step of performing sampling irradiation for irradiating the ingot with a laser beam, along a direction parallel to the second orientation flat and a plurality of directions inclined clockwise and counterclockwise by respective predetermined angles from the second orientation flat, thereby forming a plurality of sampled reduced strength areas in the ingot; and a determining step of measuring the number of nodes which exist per unit length on each of the sampled reduced strength areas, and determining a direction in which the sampled reduced strength area where the measured number of nodes is zero extends as a processing feed direction.

(Figure 5A)